

SMD Power Inductor **SEPI106012LN-SERIES-R1208**

1. Features

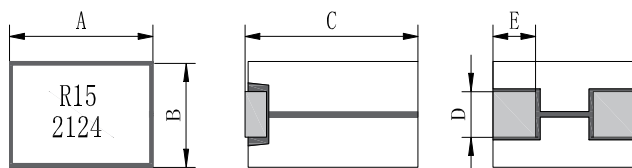
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.
5. Operating temperature:-40~+125°C (Including self - temperature rise)



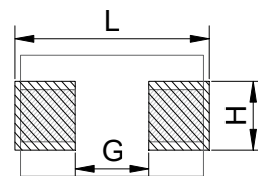
2. Applications

Commercial applications.

3. Dimensions



Recommend PC Board Pattern



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SEPI106012LN	10.0 Max	6.0 Max	12.0 Max	2.4±0.3	3.0±0.4

L(mm) Ref	G(mm) Ref	H(mm) Ref
10.3	3.9	3.0

Note: 1.PCB layout is referred to standard IPC-7351B
 2. The above PCB layout reference only.
 3. Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering



A: Series
 B: Dimension
 C: Type
 D: Inductance
 E: Inductance Tolerance
 F: Code

BxC
 Standard
 R15=0.15uH
 M=±20%
 DC Resistance , Marking direction cannot decide polarity.
 Marking: Black.R15

5. Specification

Part Number	Inductance L0 A(uH) ±20%	Irms(A) Typ	Isat (A) Typ	DCR (mΩ) ±8%
SEPI106012LN-R07M-R1208	0.07	77	150	0.125
SEPI106012LN-R10M-R1208	0.10	77	125	0.125
SEPI106012LN-R12M-R1208	0.12	77	105	0.125
SEPI106012LN-R15M-R1208	0.15	77	83	0.125
SEPI106012LN-R33M-R1208	0.33	77	40	0.125

Note:

1. Test frequency : Ls : 100KHz /0.1V.
2. All test data referenced to 20°C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 165°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.